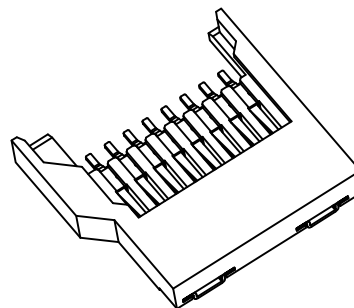
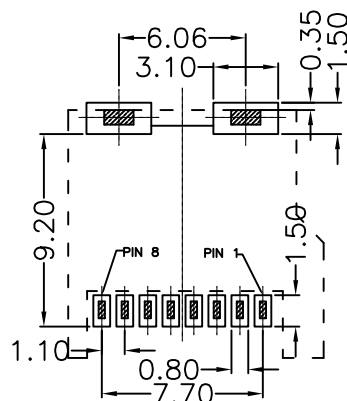
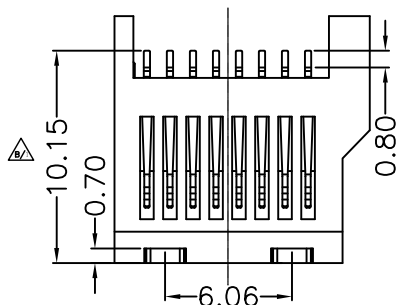
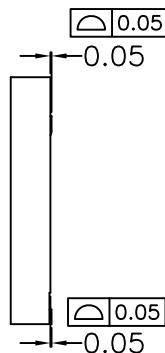
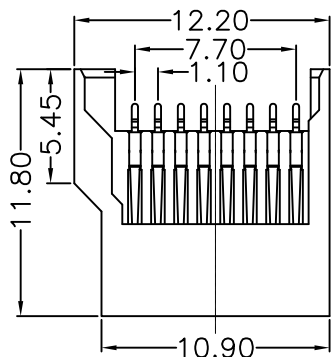
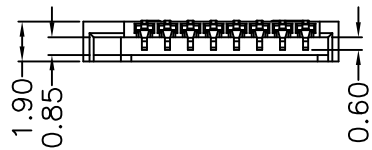


RoHS

REV	ECN NO.	DESCRIPTION	DESIGN	APPROVAL	DATE
A1	NEW	更换图框			2023.11.25



NOTES:

- MATERIAL:**
HOUSING: HIGH TEMPERATURE THERMOPLASTIC .
UL94V-0,COLOR:BLACK.
CONTACT: COPPER ALLOYS.
COVER: COPPER ALLOYS OR STEEL
- PLATING:**
UNDERPLATE: NICKEL.
CONTACT AREA: GOLD OVER NICKEL.
SOLDER AREA: TIN OVER NICKEL.
- MULTIMEDIA CARD COMPATIBLE**

订购须知:

TFS10-00S1-2000-A
1 2

1.电镀方式

S1=端子镀半金雾锡
F1=端子镀全金

2.包装方式

1=吸塑盘装
2=载带装

PIN NO.	NAME
1	DAT2
2	CD/DAT3
3	CMD
4	VDD
5	CLX
6	VSS
7	DATO
8	DAT1

3.50REF.
WORKING POSING
9.00REF.
INSERT POSITION

RECOMMENDED P.C.B HOLE
LAYOUT
COMPONENT SIDE VIEW(TOLERANCE:
+/-0.05)

X.±0.50	X.°±
.X±0.25	.X°±
.XX±0.15	.XX°±
.XXX±0.10	.XXX°±
UNITS:	mm

PART NO: TFS10-00S1-2000-A	
TITLE: T-FLASH 简易全塑卡座	
APPD	
CHKD	
DRAW	Wang
DATE	2024.01.20

XFCN 兴飞连接器

0769-82001899
www.xfconn.com

DWG NO: /

THESE DRAWINGS AND SPECIFICATIONS
ARE THE PROPERTY OF XFCN AND SHALL
NOT BE REPRODUCED, COPIED OR CUED IN
ANY MANNER WITHOUT THE PRIOR
WRITTEN CONSENT OF XFCN

VIEW	
SCALE	NONE
SHEET	1:1
REV	A1

部品料号: TFS10- 00S1-2000-A

部品描述: TF简易全塑卡座

1. SCOPE 适用范围

1.1. Content 内容

This specification covers performance, tests and quality requirements for SECURE DIGITAL MEMORY CARD CONNECTOR.TYPE B These connectors are provide space savings and improved functionality to system signal transfer.

此规范包括性能，测试及质量要求，适用于安全数字记忆卡连接器，连接器提供完善的功能系统信号传输。

2. APPLICABLE DOCUMENTS 适用文件

The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, latest edition of the specification applies. In the event of conflict between requirements of this specification and product drawing, product drawing shall take precedence.

下列文件是一个组成部分，具体规定如下(2.1)。本规范和产品图纸发生冲突，以产品图纸为准。

2.1. Commercial standards, specifications and report 商业标准，规格及报告

2.1.1. MIL-STD-1344A 根据MIL - STD - 1344a 标准

2.1.2. MIL-STD-202F 根据MIL - STD - 202f标准

3. REQUIREMENTS 要求

3.1. Design and Construction 设计与装配

Product shall be of design, construction and physical dimensions specified on applicable product drawing.

产品应在设计，装配和结构尺寸指定适用产品图纸。

3.2. Materials and Finish 材料与整理

3.2.1. Contact : High performance copper alloy (Phosphor Bronze)
Finish : (a) Contact Area: Gold over Nickel.

(b) Solder Tail area: **Tin/Lead or Tin only over Nickel.**

(c) Underplate: **50u" min. Nickel-plated all over**

端子：高性能铜合金（磷青铜）

表面处理：（a）接触部分：打镍底，镀金。

（b）焊尾区：打镍底，镀纯锡。

（c）镀膜厚：镀镍 50u"，镀锡 100"，镀金 1"。

3.2.2. **Housing : LCP+30%G.F, UL94V-0.**

胶芯材质：LCP +30 % 玻璃纤维，耐燃指数：UL94V - 0的。

3.3. Ratings 评级

3.3.1. **Voltage : 100 Volts DC,AC(rms)100 Volts (per pin)**

最大电压：100伏特直流，交流(rms).

3.3.2. **Current : 0.5 Amperes DC (per pin)**

最大电流：0.5安培直流。

3.3.3. **Operating Temperature : -25°C TO 90°C**

使用温度：-25 °C至90 °C

3.4. Performance and Test Description 性能及测试说明

Product is designed to meet electrical, mechanical and environmental performance requirements specified in Paragraph 3.5. All tests are performed at ambient environmental conditions per MIL-STD-1344A unless otherwise specified.

产品的目的是为了满足不同电气，机械和环境性能要求，在指定的第 3.5 节。所有测试是在常压环境条件下按照 MIL -STD- 1344a 除非另有说明。

3.5. Test Requirements and Procedures Summary 测试要求和程序，简易程序

Test Description 测试说明	Finally 测试结果	Condition 测试条件	
ELECTRICAL 电气			
Low-Signal Level Contact Resistance 接触电阻测试	R<30 mΩ 电阻小于 30mΩ	Mate subject connector with compatible connector as shown in. MIL-STD-202F, Method 302 500±10 %伏特之间的相邻或接触交配连接器为一分钟。 根据MIL - STD - 202f ，方法302	
SPEC NO.:	REV.: XA	ECN NO. :	PAGE : 2 / 4

XFCN 东莞市兴飞连接器有限公司

Insulation Resistance 绝缘电阻测试	R>1000 MΩ 绝缘电阻大于1000MΩ	Apply DC 500±10% Volts between adjacent contacts of mated connectors for one minute. MIL-STD-202F, Method 302 500±10 %伏特之间的相邻或接触交配连接器为一分钟。 根据 MIL - STD - 202f , 方法 302 .	
Dielectric Withstanding Voltage 介质耐电压	No discharge, flashover or breakdown. 没有放电, 烧焦或击穿。	500 V initial and 250 Vfinal for 1 minute. MIL-STD-202F, Method 301 500V 和 250V 持续一分钟。 根据 MIL - STD - 202f , 方法 301 .	
MECHANICAL 机械			
Retention Force 端子保持力	100 Gram(0.98N) minimum(per pin) 100 克 (0.98n) 最低 (每针)	Mate connector with a suitable gauge for each pin at rate of 25 mm/min. MIL-STD-1344A, Method 2012.1 用连接器与一个合适的拉力计, 每个管脚在速度为 25 毫米/每分钟情况下。 根据 MIL - STD - 1344a , 方法 2012.1	
Durability 寿命周期测试	10000 cycles. 插卡 5000 次以上。	The sample should be mounted in the at the rate of 25mm/min. MIL-STD-1344A, Method 2016 样品应装在试验机, 在指定的速 25mm/min 。 根据 MIL - STD - 1344a , 方法 2016	
Solderability 可焊性测试	Solderable area shall have minimum of 95% solder coverage. 可焊面积大于 95 %	Subject the test area of contacts into flux for 3±0.5 seconds and then into solder bath, controlled at 270±5°C, for 3±0.5 seconds. 持需焊部分进入焊料浴, 控制在270 ± 5 °C , 为3 ± 0.5秒。	
ENVIRONMENTAL 环保			
Salt Spray 氧化测试	Oxidation of not more than 5‰ 氧化面积不超过5‰	Subject mated/unmated connectors to 5±1% salt-solution concentration, 35 °C±2°C for 48 hours. MTL-STD-1344A, Method 1001.1, 以5 ± 1 %的盐溶液浓度, 35 °C ± 2 °C , 48小时。MTL-STD-1344A 1001.1	
SPEC NO.:	REV.: XA	ECN NO. :	PAGE : 3 / 4

XFCN 东莞市兴飞连接器有限公司

<p>Temperature Life (Heat Aging) (Heat Resistance) 高温测试 (热老化) (耐热)</p>	<p>A.Products in $85\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ 96 hours, the product can still be used normally. products in $85\text{ }^{\circ}\text{C} \pm 2\text{ }^{\circ}\text{C}$ 96 hours, the product can still be used normally.</p> <p>B.Products in the $260\text{ }^{\circ}\text{C} \pm 5\text{ }^{\circ}\text{C}$ or eight of the reflow temperature (maximum temperature of $260\text{ }^{\circ}\text{C}$), the deformation of not more than 0.03 mm.</p> <p>A.产品在$85^{\circ}\text{C} \pm 2^{\circ}\text{C}$ 96小时,产品仍可正常使用.</p> <p>B.产品在$260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ 或过八温段回流焊(最高温度260°C)后,变形不超过0.03mm.</p>	<p>MTL-STD-202F, Method 108A,</p>	
SPEC NO.:	REV.: XA	ECN NO. :	PAGE : 4 / 4

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [Memory Card Connectors](#) category:

Click to view products by [XFCN](#) manufacturer:

Other Similar products are found below :

[6407-249V-25273P](#) [6407-249V-25343P](#) [6426-201-21343](#) [69.920.0553.0](#) [MCR60A-98D-2.54DSA\(70\)](#) [809180410000000](#) [DM3AT-SF-PEJM5\(41\)](#) [IC11S-BUR-PNEJL\(71\)](#) [C70210M0083692](#) [2041353-2](#) [308-DS1P0811-192](#) [HM2P09PDR360N9LF](#) [10014744-011TLF](#) [11327-001](#) [11327-002](#) [NX1-32T-KT3K\(05\)](#) [95622-003LF](#) [84648-056HLF](#) [CCM03-3109 B LFT](#) [MS3116J10-6PW](#) [2309923-1](#) [61126-050CAHLF](#) [GTFP08432B1HR](#) [G85D1160022HHR](#) [SCE2MSDB76A121SN](#) [SCE2MSDZN76A121SN](#) [10014744-011ALF](#) [10014744-011LF](#) [10057542-1211FLF](#) [10067972-000LF](#) [10067972-050LF](#) [10122302-20110LF](#) [G85D1162022HHR](#) [TF-05A](#) [XKNANO-1412](#) [SMN-304-ARP6](#) [MIS11-S1F1-2000-A](#) [SMN-308-ARSP7](#) [MCS-302S-KT1B](#) [SMN-308-ACSP7](#) [K-DYX-008](#) [K-DYX-004](#) [HYCW126-TF18-150B](#) [C7024-03](#) [SMO-1030](#) [MCS-110-KT](#) [SIM-217](#) [SNO-1355-KT](#) [SMO-1025-P10](#) [SIM-211S-P6](#)